



Complex Assembly Solutions

Endicott Interconnect: Assembly Solutions that Exceed Your Expectations

Endicott Interconnect merges engineering, manufacturing, product reliability and life cycle support into assembly solutions that exceed both your expectations and industry standards.

The power of our solutions lies in the ability to provide you with a breadth of products and services all under one roof. We can build your prototypes, design a process to address a new technology, handle your assembly challenges, and then develop and execute in circuit or functional tests.

Through the broad depth of our knowledge and experience, we will help you reduce your product development time and boost your profitability during each product life cycle phase.

We will help you launch your product domestically, and then boost your profitability during volume production with our low cost capability in Shenzhen, China.

We deliver a unique mix of leading edge technology and technical expertise that gives you a time to market advantage and competitive differentiation.

And our capability and reliability meets the need of these industries:

- IT, Servers and Super Computing
- Aerospace and Defense
- Homeland Security and Government
- Industrial
- Medical
- Advanced Test Equipment

FEATURES

- Exceptional service delivered on time - 99 percent or better
- A wide range of products - from high end, complex mission critical assemblies to simpler support PCB assemblies
- Full hybrid assembly, backplane, chassis and system build
- Focused NPI to production launch, with support from dedicated program managers and engineers

QUALITY & PROCESS CONTROLS:

- Traceable systems and documentation through each product's manufacture
- Comprehensive process capabilities, including stencil design, automated solder inspection, AOI/X-ray examination, cleaning, rework/repair and high reliability testing
- Extensive testing, including FHP, ICT and FCT using both industry standard and EI developed protocols and equipment
- Top line assembly process development, including RoHS conversion and optimization
- Flexible, competitive supply chain management
- Unequaled life cycle support, including analysis, repair and upgrade, testing and more



ENDICOTT CAPABILITIES

SHENZHEN CAPABILITIES

MAXIMUM ASSEMBLY SIZE

38" x 36" (96.5 cm x 91.4 cm) for SMT
36" x 48" (91.4 cm x 122 cm)
for non-SMT backplanes
0.35" (0.9 cm) thickness

18" x 24" (457 mm x 610 mm) for SMT
18" x 24" (457 mm x 610 mm) for
non-SMT backplanes

TECHNOLOGY

SMT
Press fit
Wave solder and selective
PTH solder
Hand assembly and solder
LGA

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Press fit
Wave solder and selective
PTH solder
Hand assembly and solder

COMPONENTS

BGA/CGA down to 0.04" (1.0 mm)
µBGA and CSP down to
0.5 mm pitch
DCA wire bond and flip chip
Perimeter lead fine pitch
to 0.01" (0.25 mm)
LGA pitch down to 0.04" (1.0 mm)
SMT discretes and chips down
to 0201

BGA/CGA down to 0.03"
(0.8 mm) pitch
Perimeter lead fine pitch to 0.01"
(0.25 mm)
SMT discretes and chips down to 0402

CORE PRODUCT

Very thick PCBs; high-density
hybrid assemblies (average
components >1500); double-sided,
large complex boards with mixed
technology
Hybrid assemblies
(SMT/PTH/press fit)
Components: high I/O area array
modules (CGA, LGA, PBGA)
Connectors: dense, high
I/O connectors
Mechanical: cage, chassis,
system assemblies
High density BGA/area
array rework

High-density hybrid assemblies
(average components >1500);
double sided, complex boards with
mixed technology
Hybrid assemblies (SMT/PTH/press fit)
Components: high I/O area array
modules (CGA, PBGA)
Connectors: dense, high I/O
connectors
Mechanical: cage, chassis, system
assemblies

TESTING

Teredyne 2286, 2287LX, 2287LX
Ultraprobe
Scorpion Flying Probe
Functional system level
ESS and burn-in

Teredyne 2287
Functional system level

CERTIFICATIONS

AS 9100
ISO 9001
ISO 13485
ISO 14001
IPC-A-610
JSTD 001

IPC-A-610
ISO 13485



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